

MEMS MICROPHONE PACKAGE

ABSTRACT OF THE DISCLOSURE

Provided is a MEMS microphone package that can shield a MEMS microphone chip from noise to greatly improve sound quality and reduce manufacturing costs, by inserting a PCB substrate to which the MEMS microphone chip is mounted into a metal case, and then by ground-connecting the metal case to a main board using an assembly process including bending and clamping an end of the case. The MEMS microphone package includes a tetragonal container-shaped metal case having an open-side to insert components into an inner space, and a chamfered end on the open-side to easily perform a curling operation, a PCB substrate to which a MEMS microphone chip and an ASIC chip are mounted, the PCB substrate being inserted into the case, and a support configured to support the PCB substrate and define a space between the case and the PCB substrate.

Figure 2